Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	14	"6025648".pn. "6324069".pn. "5854507".pn. "5883426".pn. "6563712".pn. "6580169".pn. "6121682".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 13:27
S2	1093	(underfill or encapsulant or encapsulation or encapsulating or molding or mold) near2 (barrier or dam or wall or ridge) near10 (chip or die or integrated adj circuit)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/18 15:16
S3	216	(underfill or encapsulant or encapsulation or encapsulating or molding or mold) near2 (barrier or dam or wall or ridge) near10 (chip or die or integrated adj circuit) and (chip or die or integrated adj circuit) near3 (package or packaging or housing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 10:42
S4	4	("5278446" | "5729050" | "6239480" | "6391682").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/18 17:03
S5	44	(underfill or encapsulant or encapsulation or encapsulating or molding or mold) near6 (control or controlling or regulating or regulation or regulated or controlled) near6 (barrier or dam or wall or ridge or bump or post or standoff or raised) and (chip or die or integrated adj circuit) near3 (package or packaging or housing)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 10:52
S6	24	("20030038381" | "5120678" | "5336931" | "5450283" | "5541450" | "5583378" | "5646828" | "5674785" | "5739585" | "5766982" | "5808873" | "5831832" | "5834835" | "5895965" | "5909056" | "5963429" | "6046077" | "6049094" | "6071761" | "6197614" | "6248951" | "6359335" | "6472598" | "6555906"). PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/19 10:54
S7	42	("5766982").URPN.	USPAT	OR	ON	2005/08/19 11:01
S8	29	("3926746" | "4681656" | "4792646" | "4802277" | "4849856" | "4910584" | "4970579" | "4999740" | "5027191" | "5045921" | "5057969" | "5115964" | "5133495" | "5136366" | "5153385" | "5159535" | "5170931" | "5191511" | "5203075" | "5241133" | "5261155" | "5280193" | "5291062" | "5294750" | "5332864" | "5345106" | "5357672" | "5381039" | "5420460").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/19 11:18
S9	107	("5583378").URPN.	USPAT	OR	ON	2005/08/19 13:39
S11	369	(wall or stencil or barrier or ridge or raised or standoff or socket or recess$) near4 (around or surround$4 or circumscribing) near4 (die or chip or ic) and (encapsula$5 or mold or molding or underfill$4) and (chip or die or ic or integrated adj circuit) near3 (package or packaging or housing or packaged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 13:44
S12	89	(wall or stencil or barrier or ridge or raised or standoff or socket or recess$) near4 (around or surround$4 or circumscribing) near4 (die or chip or ic) same (encapsula$5 or mold or molding or underfill$4) and (chip or die or ic or integrated adj circuit) near3 (package or packaging or housing or packaged)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 13:45
S13	16	("5841194").URPN.	USPAT	OR	ON	2005/08/19 14:35
S14	94	438/124.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 15:24
S15	115	438/126.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/19 16:14

S16	289	438/127.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 10:24
S17	109	257/667.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 11:17
S18	45	257/790.ccor.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 11:17
S19	16	(US-20020060084-$ or US-20020185717-$ or US-20020192876-$ or US-20020195703-$ or US-20030183909-$ or US-20030183950-$ or US-20040178515-$ or US-20050023572-$).did. or (US-5583378-$ or US-5817545-$ or US-5841194-$ or US-6025648-$ or US-6324069-$ or US-6400036-$ or US-6486562-$ or US-6653720-$).did.	US-PGPUB; USPAT	OR	ON	2005/08/23 10:59
S20	8	("5089440" | "5218759" | "5285352" | "5302849" | "5371404" | "5659203" | "5864178" | "5900581").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 12:00
S21	12	("6093972").URPN.	USPAT	OR	ON	2005/08/23 12:03
S22	602	(chip or die or ic or integrated adj circuit) near4 (package or packaging or housing) and (chip or die or ic or integrated adj circuit) near5 (underfill$4) and (chip or die or ic or integrated adj circuit or package or packaging or housing) near4 (lid or cover)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 13:29
S23	236	(chip or die or ic or integrated adj circuit) near4 (package or packaging or housing) and (chip or die or ic or integrated adj circuit) near5 (underfill$4) and (chip or die or ic or integrated adj circuit or package or packaging or housing) near4 (lid or cover) near10 (encapsulant or encapsulation or resin or epoxy or adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/23 13:29
S24	15	("4788767" | "5371404" | "5777847" | "5796170" | "5811317" | "5866943" | "5879786" | "5895967" | "5955789" | "6020221" | "6051888" | "6144101" | "6313521" | "6437436" | "6504096").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/23 14:05